CSTIC 2023 Summary

June 26-July 27, 2023

Shanghai, China

www.semicronchina.org/cstic  v.semi.org.cn/cstic
Plenary Session and Award Winners
Plenary Speakers

Spintronics for Greener Digital Technologies and Prospects Far Beyond

Prof. Albert Fert
Research Director, Unité Mixte de Physique, Nobel Laureate in 2007

Innovations Boost Integrated Circuit

Prof. Ming Liu
Academician of CAS, Fudan University

Advanced Packaging Technology Challenges: an Equipment Supplier's Perspective

Dr. Yang Pan
Corporate Vice President, Lam Research

Endless Technological Innovation in IC Equipment

Mr. Jinrong Zhao
Chairman of the Executive Committee, Beijing NAURA Technology Group

From Legacy to Leading Edge: Broadband Wafer Optical Inspection for Process Control

Dr. Yalin Xiong
Senior Vice President and General Manager, KLA Corporation
>170 Oral Presentations and >180 Posters
9 Symposia with 100 Invited Speakers

Symp I: Device Engineering and Memory Technology
Symp. II: Lithography and Patterning
Symp. III: Dry & Wet Etch and Cleaning
Symp. IV: Thin Film, Plating and Process Integration
Symp. V: CMP and Post CMP Cleaning
Symp. VI: Metrology, Reliability and Testing
Symp. VII: Packaging and Assembly
Symp. VIII: MEMS, Sensors and Emerging Semiconductor Technologies
Symp. IX: Design and Automation of Circuits and Systems

Virtual Conference: June 29-July 26  v.semi.org.cn/cstic
Largest and most comprehensive, influential annual industrial semiconductor technology conference in China and Asia.

403 abstract submissions have been collected. 724 registered attendees joined the onsite conference, while online registration is 1061, including oversea attendees from US, Israel, Japan, Korea, Germany, Sweden, Switzerland, Singapore, UK, Russia, Canada, France, Saudi Arabia, Taiwan China, HK China and etc.
CSTIC Symposium Abstract Submission

Symp IX - Design and Automation of Circuits and Systems, 54
Symp VIII - MEMS, Sensors and Emerging Semiconductor Technologies, 22
Symp VII - Packaging and Assembly, 16
Symp VI - Metrology, Reliability and Testing, 57
Symp V-CMP and Post CMP Cleaning, 26
Symp IV - Thin Film, Plating and Process Integration, 47
Symp III - Dry & Wet Etch and Cleaning, 76
Symp II - Lithography and Patterning, 34
Symp I - Device Engineering and Memory Technology, 66

*Totally 205 manuscripts published at IEEE
Industry and Academy Cooperation
67% Attendees from Industry

- 67% attendees from industry
- 30% attendees from academy
- Attendees were from around 190 different companies or institutes
- Chip companies like SMIC, HLMC, HHGrace, JCET, CXMT, CXMC, NXP, Wuhan Xinxin, Intel, AMD and etc. joined the conference
190 Participating Companies

5N Plus China
AAA
ACM
ADVANTEST
Air Liquide
Air Products
AMD
AMEC
Ancu Technology
Anji
Applied Materials
ASM
ASML
Axcelis
BDA
Beihang University
Beihang University Hefei Research Institute
Beijing Integrated Circuit Equipment Innovation Cente
Beijing Jiaotong University
Beijing Nauer
Beijing NeuCloud
Beijing sunrise Technology
Beijing Superstring Memory Research Institute
Beijing University of Chemical Technology
Bobei Chemical
BOE
Bonotec Electronic Materials
Canon
CanSemi Technology
China University of Mining & Technology
China University of Politics and Law
CMT
Cymer
D2S Inc.
DJEL (Beijing)
DuPont
Edwards
Embassy of Canada
Fraunhofer Institute for Electronic Nano Systems
French institute for Scientific Research
Fudan University
Fujian Jinhua Integrated Circuit
Fujifilm
Fujimi
Giga-da
GIICS
Global Research & Innovative Solutions Co., Ltd.
Guangdong University of Technology
Guangdong University of Technology
Haohua Gas
Hebei University of Technology
HFC Semiconductor
HIGrace
H Knight Microelectronics
Hitachi High-tech
HLMC
Hong Kong Polytechnic University
Huahong Semiconductor
Huangshan University
Huawei
Huazhong University of Science and Technology
HWSHING Technology
IBM
ICT, CAS
Ideal Energy Sunflower
IMECAS
Indium Corporation
Infinitesima Ltd
Intel
ENAKET
Jiangsu LeadMicro Nano Technology
Jinan Shengquan Group
Jinhua Integrated Circuit
JSR
Kioxia
KLA
Lam Research
Lanzhou University of Technology
Leuven Instruments
Liverpool John Moores University
Mayair
Mentor Graphics
Nanjing University
Nanjing University of Posts and Telecommunications
National Central University
National Institute of Metrology
Ningbo University
Nova Ltd
NXP
ONTO
Panasonic
PARC S.R.L. LLC
190 Participating Companies

- Peking University
- Pengxinwei Semiconductor
- Piotech
- Qunyi Mask Optoelectronics Technology
- Radiant Shore
- Raintree Scientific Instruments (Shanghai) Corporation
- S.Y. Technology Engineering & Construction
- Sanechips Technology
- School of Integrated Circuits, Chinese Academy of Sciences
- Shandong Shengquan New Materials
- Shanghai Institute of IC Materials
- Shanghai Jiao Tong University
- Shanghai United Imaging Healthcare
- Shanghai University
- Shanghaitech University
- Shenzhen China Star Optoelectronics Semiconductor Display Technology
- Shenzhen University
- Shinko Control Technology
- Siemens
- Sky Semiconductor
- SMIC
- SMNC
- Southwest Jiaotong University
- STIC
- SUSTECH
- Suzhou Runbang
- Suzhou STR Software Technology
- Synopsys
- Taiwa...
WFD Training Courses

Lithography process and key technical aspects in exposure tools, materials, and the future development roadmap

Dr. Qiang Wu, Professor of the School of Microelectronics of Fudan University

Post CMP Cleaning

Dr. Jin-Goo Park, Professor of Hanyang University, Korea
## Attendees to Plenary Session and 9 Symposia

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Conference Chair and Co-Chairs

Dr. Hanming Wu
Conference Chair

Prof. Ru Huang
Conference Co-Chair

Prof. Cor Claeys
Conference Co-Chair

Dr. Steve X. Liang
Conference Co-Chair

Dr. Beichao Zhang
Conference Executive Co-Chair

Dr. Qinghuang Lin
Conference Co-Chair
Symposium Chairs

Dr. Ru Huang
Symp-I Chair, Conference Co-Chair
Professor of Peking University,
President of Southeast University,
Academician of Chinese Academy of Sciences

Dr. Linyong (Leo) Pang
Symp-II Chair
Vice President, D2S Inc., USA

Dr. Ying Zhang
Symp-III Chair
Consultant

Dr. Xiaoping Shi
Symp-IV Chair
CTO, Beijing Naura Microelectronics, China

Dr. Xinping Qu
Symp-V Chair
Professor, Fudan University, China

Dr. Xiaowei Li
Symp-VI Chair, Deputy Director, ICT, CAS, China

Dr. Steve X. Liang
Symp-VII Chair

Dr. Qinghuang Lin
Symp-VIII Chair Director,
Lam Research, USA

Prof. Weikang Qian
Symp-IX Chair
Assistant Professor, University of Michigan-Shanghai Jiao Tong University Joint Institute, China

Dr. Hsiang-Lan Lung
Poster Chair
Director, MXIC, Taiwan, China
Special Thanks to Sponsors and Co-organizers
CSTIC 2024

Time: March 17 ~ 18, 2024

CSTIC 2024 call for papers and manuscript deadlines:

Abstract Due: Sep. 30, 2023
Author Notification: Oct. 15, 2023
Manuscript Due: Dec. 26, 2023

Copyright Due: Feb. 20, 2024
Presentation Due: Feb. 20, 2024
Conference Date: Mar. 17-18, 2024
Thank you